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(Rev. 03/01) OMB No. 0651-0027 (exp. 5/31/2002)		
To the Honorable Commissioner c. 10205112	25ached original documents or copy thereof.	
1. Name of conveying particlies):		
Teruo KISU Haruko KISEMARKO	2. Name and address of receiving party(ies)	
(successor in right to Teruaki KISU)	Name: HITACHI, LTD. Internal	
Kazuo NAKA <b>Z</b> ATO	Address: <u>6, K</u> anda Surugadai 4-chome	
Masahito TAKAHASHI	Street Address: Chiyoda-ku,	
	City: Tokyostate: Japanzip:	
Additional name(s) of conveying party(ies) attached?   Yes   No	☑ Other	
Nature of conveyance:	Hitachi ULSI Systems Co., Ltd.	
	22-1, Josuihoncho 5-chome	
☐ Security Agreement ☐ Change of Name	Kodaira-shi, Tokyo, Japan	
☐ Other	- ,	
Execution Date: $12-17/28-01 \& 1-4-02$	Additional name(s) & address(es) attached?   Yes   No	
Application number(s) or patent number(s):		
If this document is being filed together with a new application, the		
A. Patent Application No.(s)	B. Patent Registration No.(s)	
Serial No. 10/026,769		
Filed: December 27, 2001		
Additional number(s) att	ached Li Yes & No	
<ol><li>Name and address of party to whom correspondence concerning document should be mailed:</li></ol>	Total number of applications and patents involved	
Name: Antonelli, Terry, Stout & Kraus, LLP	7. Total fee (37 CFR 3.41)\$40.00	
Name. Supplies, 18119, Many M. Mana, LL.	☑ Enclosed	
	LA Enclosed	
Internal Address:	Authorized to be charged to deposit account	
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Suite 1800	Deposit account number:	
Arlington, VA 22209		
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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true		
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	04/05/2002	
William I. Solomon William I. Solomon 04/05/2002		
Name of Person Signing Signatur	e Date	

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PATENT REEL: 012766 FRAME: 0006

## **ASSIGNMENT**

(譲渡証)

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to Teruaki KISU, Kazuo NAGASATO and Masahito TAKAHASHI,

citizens of Japan by HITACHI, LTD., and Hitachi ULSI Systems Co., Ltd., corporations organized under the laws of Japan,

located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 22-1, Josuihoncho 5-chome,

Kodaira-shi, Tokyo, Japan, respectively,

receipt of which is hereby acknowledged, we, the said Teruaki KISU, Kazuo NAGASATO and Masahito TAKAHASHI

do hereby sell and assign to said HITACHI, LTD., and Hitachi ULSI Systems Co., Ltd.,

their successors and assigns, all our right, title and interest, in and for the United States of America, in and to METHOD OF MANUFACTURING SEMICONDUCTOR MEMORY DEVICE AND

## SEMICONDUCTOR MEMORY DEVICE

invented by us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., and Hitachi ULSI Systems Co., Ltd.,

their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made:

And we hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., and Hitachi ULSI Systems Co., Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed (署名日)

1)	木須 昭夫	December 28, 2001
, .	(Teruaki KISU, deceased by Teruo KISU, Legal Representative)	
2)	木須治子	December 28, 2001
_, .	(Teruaki KISU, deceased by Haruko KISU, Legal Representative)	
3)		
<b>3</b> )	(Kazuo NAKAZATO)	
	(	
4)		
	(Masahito TAKAHASHI)	

PATENT REEL: 012766 FRAME: 0007

## **ASSIGNMENT**

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## METHOD OF MANUFACTURING SEMICONDUCTOR MEMORY DEVICE AND

SEMICONDUCTOR MEMORY DEVICE invented by us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., and Hitachi ULSI Systems Co., Ltd.,

their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made;

And we hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., and Hitachi ULSI Systems Co., Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

	•
(Teruaki KISU, deceased by Teruo KISU, Legal Representative)	
(Teruaki KISU, deceased by Haruko KISU, Legal Representative)	
Kagno Natorato	4/January 12002
(Kazuo NAKAZATO)	<b>O</b>
Masshita Takahashi	17/ December /2001
(Masahito TAKAHASHI)	

PATENT REEL: 012766 FRAME: 0008

Date Signed

(署名目)

RECORDED: 04/05/2002